

Mike Sullivan

CVP, INVESTOR RELATIONS



Michael Sullivan is corporate vice president and head of Investor Relations. His team is responsible for investor relations and marketing communications including media relations, product and technology communications, and industry events.

Mr. Sullivan joined Applied in 2009 after working at Intel Corporation for 16 years. He was Intel's primary interface to equity analysts and the company's largest institutional shareholders in the U.S. and Europe. He also held corporate communications positions at the company's U.S. and European offices, where he drove corporate and competitive initiatives, new microprocessor introductions, computing platform campaigns, and flash memory PR.

Mr. Sullivan is past president of the Silicon Valley chapter of NIRI, the National Investor Relations Institute. He earned his MBA at Santa Clara University and his BA in Public Relations at San Jose State University.

Chidi Chidambaram, Ph.D.

VP, ENGINEERING



Chidi Chidambaram leads the process technology and foundry engineering team at Qualcomm as Vice President Engineering. Qualcomm is a leader among the fab less industry in bringing leading edge semiconductor technologies to manufacturing - Qualcomm was the first company to ship large volume products in 10 nm technology in 2017. Chidi's team is also responsible for RF devices based on finlet and SOI transistors. Earlier Chidi developed silicon technology at Texas Instruments and was instrumental in the first embedded SiGe implementation by semiconductor Industry. Chidi is recognized as a IEEE fellow for contribution to strain engineering and Design technology co-optimization (DTCO). Chidi's 20+ year semiconductor career has evenly straddled research and development with over 60 each of refereed articles and patents.

Uday Mitra, Ph.D.

VP, ENGINEERING



Dr. Mitra has almost 4 decades of experience in the semiconductor industry managing technology integration, lithography, etch, thin films and packaging modules for both logic and memory products. Prior to joining Applied in 2005, he was director of technology integration at Intel Corporation, where he spent 17 years holding various management positions. Uday received his Ph.D. in Materials Science from MIT and is a recipient of the Henry Marion Howe Medal from the American Society of Materials International.

Michael Chudzik, Ph.D.

VP, TECHNOLOGY



Michael Chudzik is currently a Vice President of Technology. He manages teams of device integrators, process and device engineers and program managers to execute on large scale device fabrication projects. He has been in several device Integration leadership roles during his 7 years at Applied Materials. Prior to Applied Materials, Mike was at IBM for 14 years where he led teams in the R&D of advanced semiconductor process integration. He received his Ph.D. in Electrical Engineering at Northwestern University.

Mehul Naik, Ph.D.

MD, Principal Member of Technical Staff



Mehul Naik is Managing Director and Principal Member of Technical staff with the Advanced Product Technology Development team in the Semiconductor Products Group at Applied Materials. He is responsible for the Logic Program working on inflection mapping and leading cross-functional programs in the Transistor and Interconnect area. He has authored over 60 publications and holds over 70 U.S patents. Mehul holds a Ph.D. in Chemical Engineering from Rensselaer Polytechnic University.

Regina Freed

MD, Patterning Technology Development



Regina Freed is Managing Director of Patterning Technology of Applied Materials. She has more than 20 years of experience in the semiconductor industry, managing semiconductor process and equipment development for both logic and memory processes, including co-optimization between deposition and etch, lithography, metrology, and defect inspection. At Applied Materials, Regina manages programs that focus on material engineering solutions to advanced patterning applications, enabling customers to scale faster and at lower cost, while optimizing device performance.

Raman Achutharaman Ph.D.

GVP, Head of Technology, Strategy, and Marketing



Dr. Raman Achutharaman is group vice president and head of the technology, strategy, and marketing group for the Semiconductor Products Group with responsibility for defining the technology roadmap, developing the strategic plan to strengthen the company's leadership in core wafer fabrication equipment markets, and effectively communicating the vision, strategy, and success to stakeholders.

Dr. Achutharaman has a diverse technical background and a strong track record for commercializing successful products. Prior to current role, Dr. Achutharaman was the general manager of the Etch and Selective products business unit where he led the development and commercialization of Sym3 etch product which resulted in growing the etch revenue from less than \$400M to over \$2B and gaining over 15 pts of share in Conductor Etch. Previously as general manager of the RTP product group, he led development of the Radiance product which has been foundational to Applied's market leadership in thermal processing.

Dr. Achutharaman received his undergraduate degree in metallurgical engineering from the Indian Institute of Technology, Chennai, India and his doctorate in materials science and engineering from the University of Minnesota. He has published more than 20 papers, review articles and book chapters, and holds multiple patents.